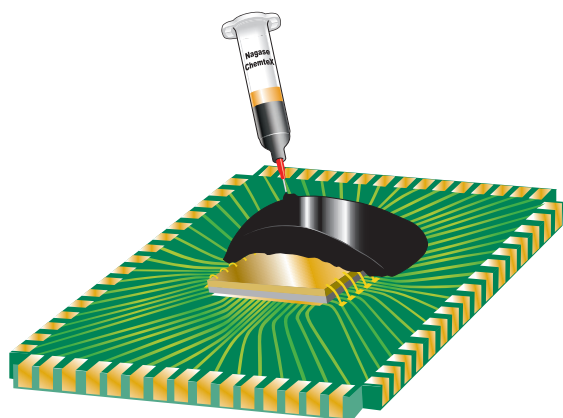


Chip Encapsulants



- **Glob Top**
- **Cavity Fill**
- **Dam and Fill**
- **MCM Encapsulation**

PRODUCT	DESCRIPTION	VISCOSITY 19 s ⁻¹ (cP)	T _g TAN δ (°C)	CURE SCHEDULE	POT LIFE @ 25°C (hr)
Chip on Board Encapsulants					
EN-7826	Glob top encapsulant. User friendly pot life (> 2 days), superior environmental protection with enhanced moisture resistance and internal stress relief. CTE α ₁ (<T _g) ≈ 18ppm/°C	65,000	140	30 min @ 150°C	>48
DE-7826	Dam fill material. Matches cavity properties. User friendly pot life (>2 days), superior environmental protection with enhanced moisture resistance and internal stress relief. CTE α ₁ (<T _g) ≈ 18ppm/°C	200,000	140	30 min @ 150°C	>48
CE-7826	Cavity fill material. Matches dam properties. Excellent flow properties, user friendly pot life (> 2 days), superior environmental protection with enhanced moisture resistance and internal stress relief. CTE α ₁ (<T _g) ≈ 18ppm/°C	40,000	140	30 min @ 150°C	>48
UV Cure Chip Encapsulants					
DC-4261	Dam material for dam and fill chip encapsulation. Good for smart cards and general circuit assembly applications	10,000	112	UV and/or 30 min @ 150°C	72
DC-4262	Fill material for dam and fill chip encapsulation. Good for smart cards and general circuit assembly applications	2,000	72	UV and/or 30 min @ 150°C	72

 **Nagase Chemtex America**